



Material Content Data Sheet



Sales Product Name		BGA 7L1N6 E6327		Issued		25. January 2018		
MA#		MA001122056						
Package		PG-TSNP-6-2		Weight*		0.92 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.093	10.16	10.16	101584	101584
bumps	non noble metal	copper	7440-50-8	0.003	0.33	0.33	3308	3308
leadframe	non noble metal	tin	7440-31-5	0.001	0.10		971	
	non noble metal	zinc	7440-66-6	0.001	0.08		777	
	non noble metal	chromium	7440-47-3	0.001	0.12		1166	
encapsulation	non noble metal	copper	7440-50-8	0.353	38.55	38.55	385641	388555
	organic material	carbon black	1333-86-4	0.002	0.22		2240	
	plastics	epoxy resin	-	0.060	6.50		64958	
	inorganic material	silicondioxide	60676-86-0	0.349	38.08	44.80	380788	447986
leadfinish	non noble metal	tin	7440-31-5	0.037	4.06	4.06	40550	40550
plating	noble metal	silver	7440-22-4	0.015	1.62	1.62	16200	16200
solder	noble metal	silver	7440-22-4	0.000	0.00		41	
	non noble metal	tin	7440-31-5	0.002	0.18	0.18	1776	1817
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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